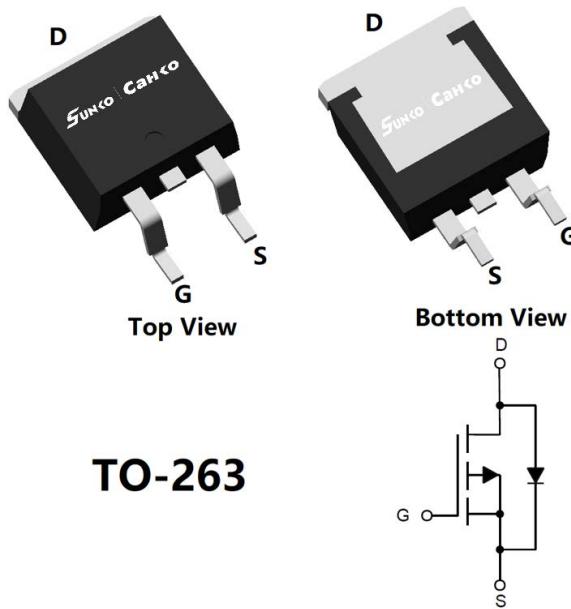


P-Channel Enhancement Mode Field Effect Transistor



Product Summary

- V_{DS} -100V
- I_D -30A
- $R_{DS(ON)}$ (at $V_{GS}=-10V$) <56 mohm
- $R_{DS(ON)}$ (at $V_{GS}=-4.5V$) <62 mohm
- 100% EAS Tested
- 100% ∇V_{DS} Tested

General Description

- Split gate trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- DC-DC Converters
- Power management functions

■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	-100	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current	Tc=25°C	I_D	-30	A
	Tc=100°C		-19.2	
Pulsed Drain Current ^A		I_{DM}	-120	A
Avalanche energy ^B		E_{AS}	162	mJ
Total Power Dissipation ^C	Tc=25°C	P_D	125	W
	Tc=100°C		50	
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	°C

■ Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient ^D	$t \leq 10\text{s}$	$R_{\theta JA}$	12	15	°C/W
Thermal Resistance Junction-to-Ambient ^D	Steady-State		50	60	
Thermal Resistance Junction-to-Case	Steady-State		0.8	1.0	

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SCB30GP10A	F2	SCB30GP10A	800	/	8000	13" reel

■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-100\text{V}, V_{\text{GS}}=0\text{V}$	$T_J=25^\circ\text{C}$		-1	μA
			$T_J=55^\circ\text{C}$		-5	
			$T_J=125^\circ\text{C}$		-10	
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-1.8	-2.5	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}= -10\text{V}, I_{\text{D}}=-15\text{A}$		42	56	$\text{m}\Omega$
		$V_{\text{GS}}= -4.5\text{V}, I_{\text{D}}=-7\text{A}$		46	62	
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=-15\text{A}, V_{\text{GS}}=0\text{V}$			-1.3	V
Maximum Body-Diode Continuous Current	I_{S}				-30	A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=-50\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		2100		pF
Output Capacitance	C_{oss}			236		
Reverse Transfer Capacitance	C_{rss}			48		
Switching Parameters						
Total Gate Charge	$Q_g(-10\text{V})$	$V_{\text{GS}}=-10\text{V}, V_{\text{DS}}=-50\text{V}, I_{\text{D}}=-5\text{A}$		40		nC
Total Gate Charge	$Q_g(-4.5\text{V})$			19.4		
Gate-Source Charge	Q_{gs}			7.8		
Gate-Drain Charge	Q_{gd}			8.6		
Reverse Recovery Charge	Q_{rr}	$I_{\text{F}}=-5\text{A}, di/dt=100\text{A/us}$		280		ns
Reverse Recovery Time	t_{rr}			104		
Turn-on Delay Time	$t_{\text{D(on)}}$			13		
Turn-on Rise Time	t_r	$V_{\text{GS}}=-10\text{V}, V_{\text{DD}}=-50\text{V}, I_{\text{DS}}=-5\text{A}$ $R_{\text{GEN}}=6\Omega$		39		ns
Turn-off Delay Time	$t_{\text{D(off)}}$			100.1		
Turn-off fall Time	t_f			105.3		

- A. Repetitive rating; pulse width limited by max. junction temperature.
 B. $V_{\text{DD}}=50\text{V}, R_G=25\Omega, L=0.5\text{mH}$.
 C. P_d is based on max. junction temperature, using junction-case thermal resistance.
 D. The value of $R_{\theta JA}$ is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with $TA = 25^\circ\text{C}$. The Power dissipation P_{DSM} is based on $R_{\theta JA} \leq 10\text{s}$ and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.

■ Typical Performance Characteristics

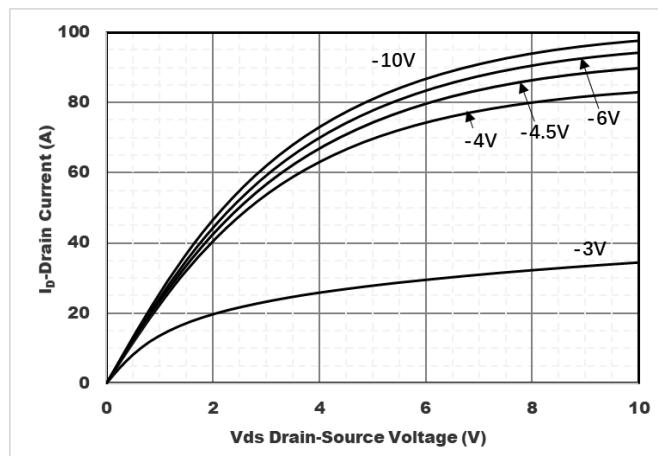


Figure1. Output Characteristics

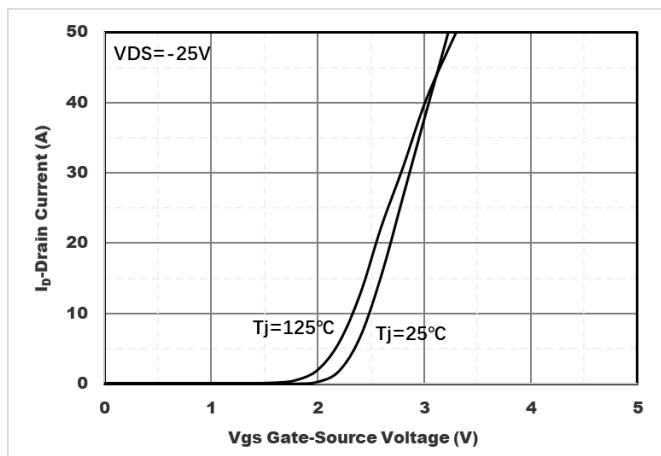


Figure2. Transfer Characteristics

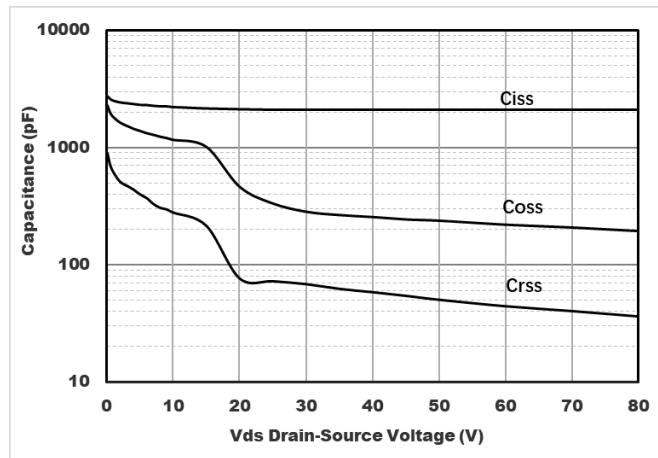


Figure3. Capacitance Characteristics

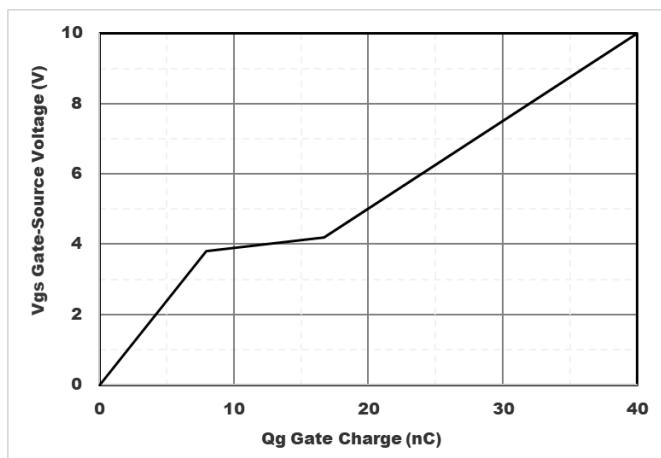


Figure4. Gate Charge

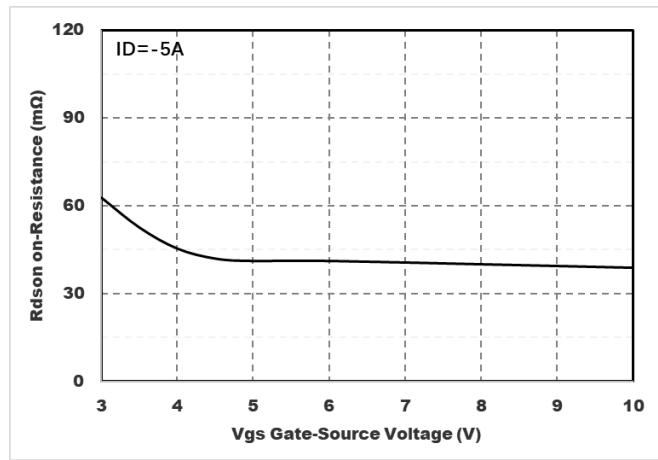


Figure5. : On-Resistance vs. Gate to Source Voltage

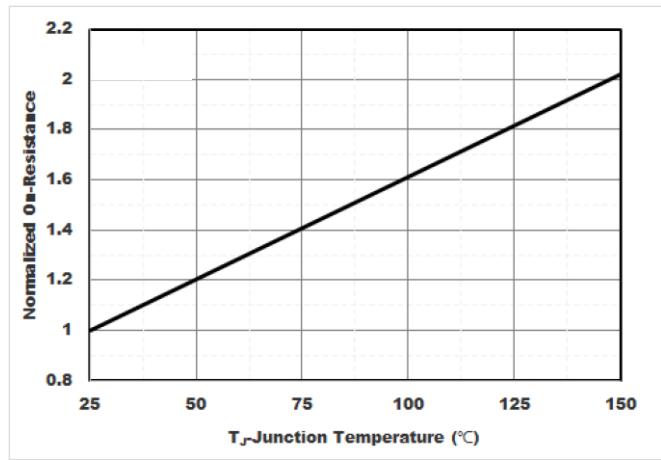


Figure6.Normalized On-Resistance

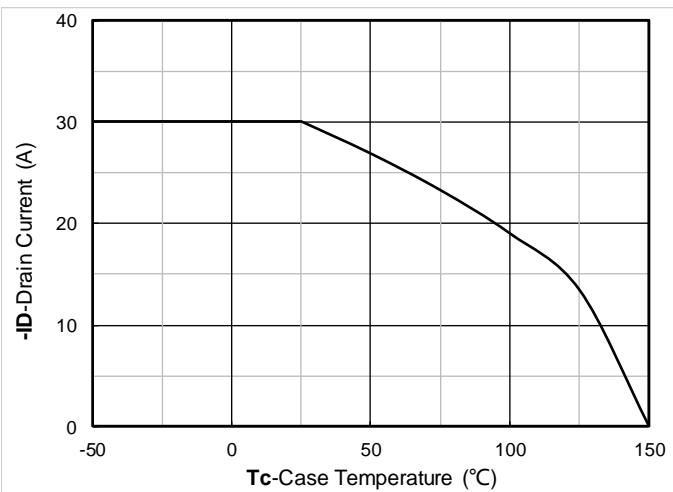


Figure 7. Drain current

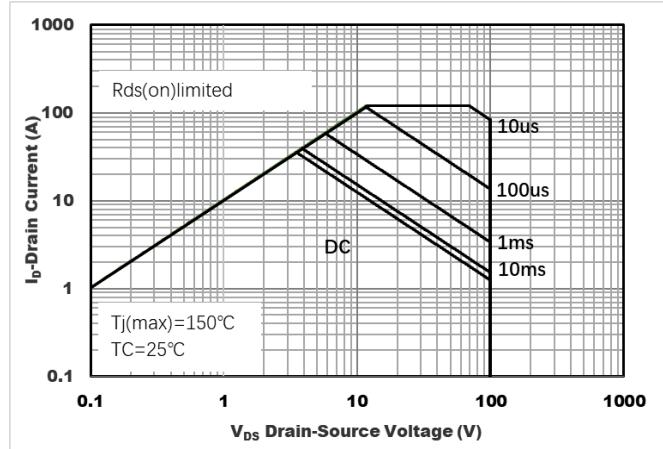


Figure 8. Safe Operation Area

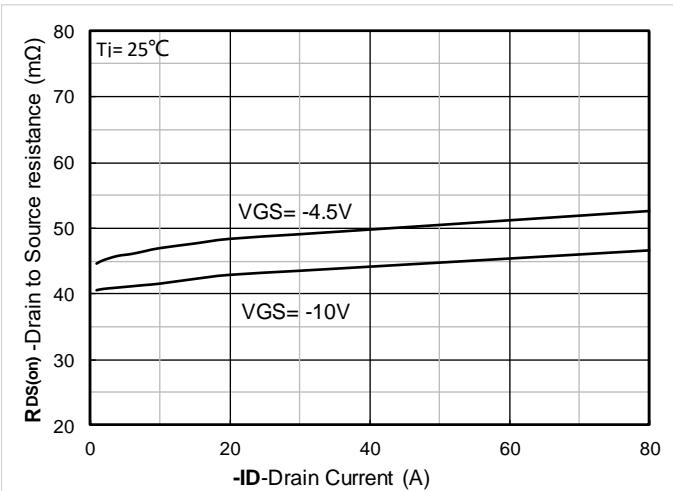
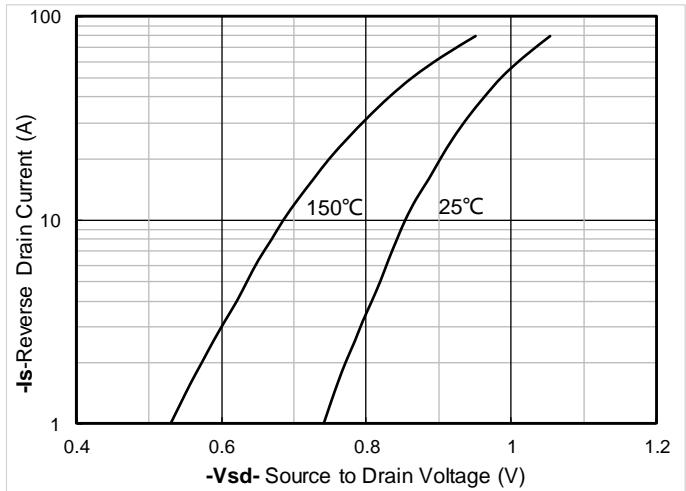
Figure 9. R_{DS(on)} VS Drain Current

Figure 10. Forward characteristics of reverse diode

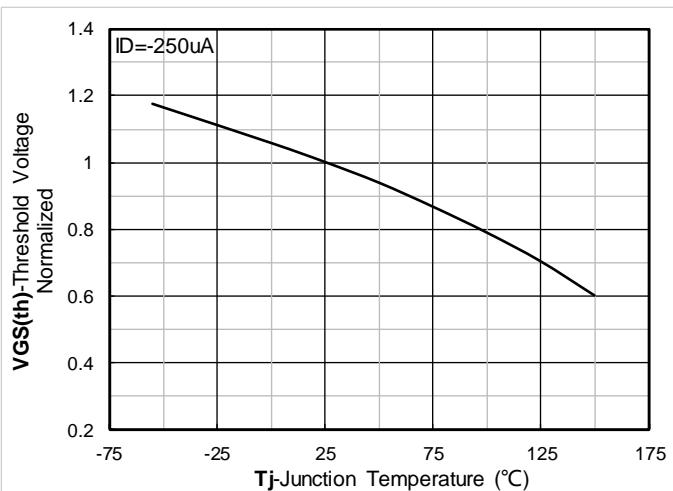


Figure 11. Normalized Threshold voltage

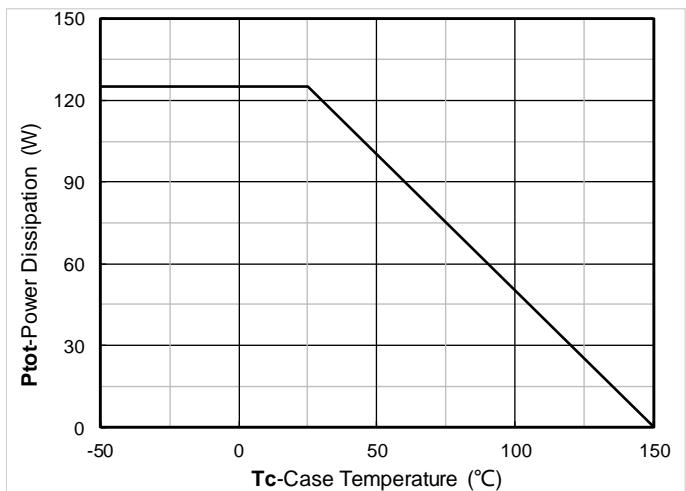


Figure 12. Power dissipation

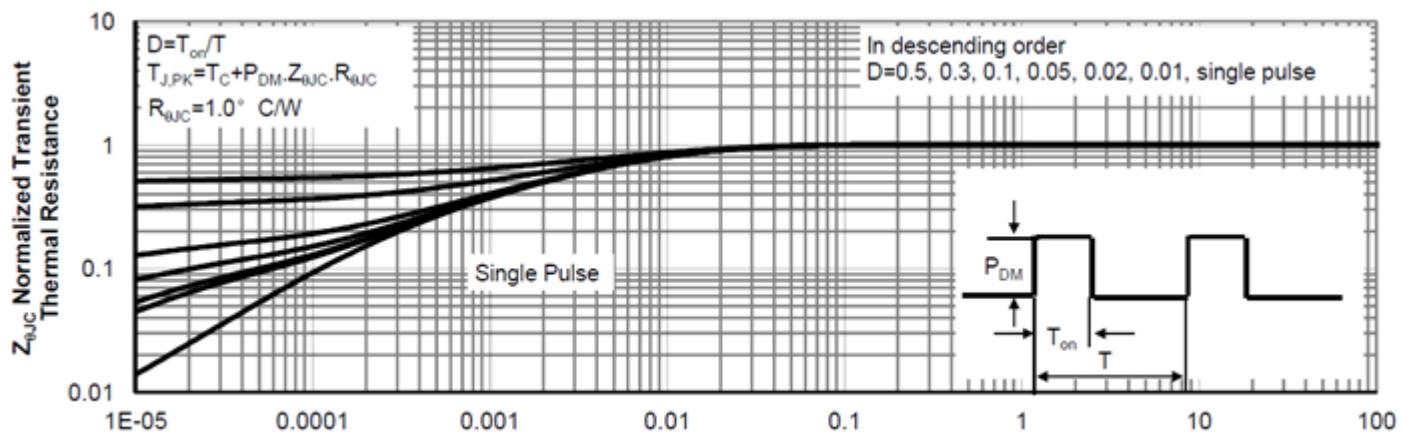
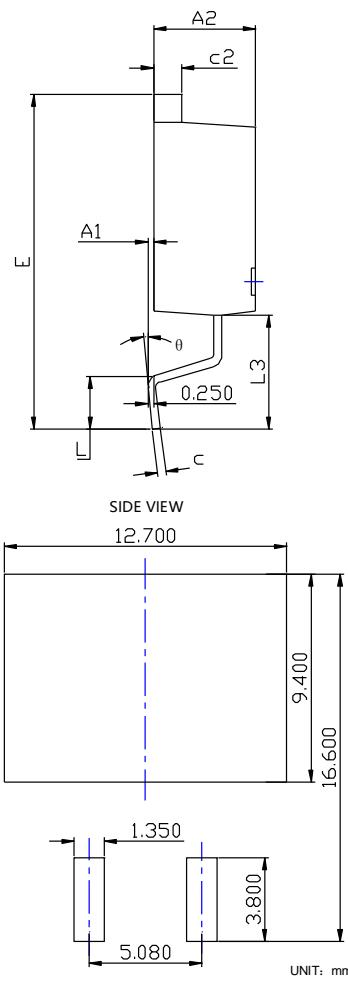
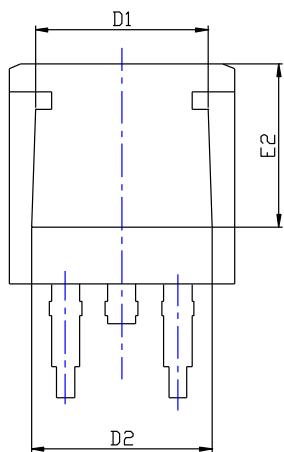
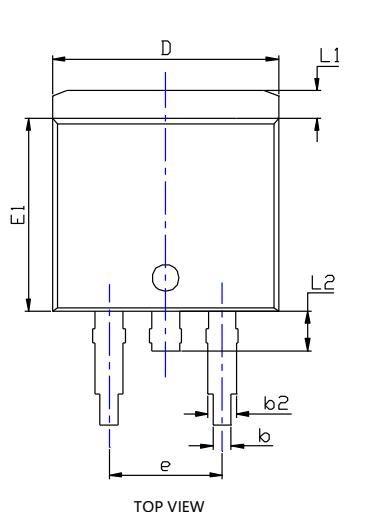


Figure13.Normalized Maximum Transient thermal impedance

■ TO-263-HY Package information



SYMBOL	INCHES			Millimeter		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A1	0.000	---	0.010	0.000	---	0.250
A2	0.174	0.180	0.186	4.430	4.580	4.730
b	0.028	0.032	0.036	0.720	0.820	0.920
b2	0.046	0.050	0.054	1.180	1.280	1.380
c	0.013	0.015	0.018	0.330	0.390	0.450
c2	0.048	0.050	0.053	1.220	1.280	1.340
D	0.394	0.400	0.406	10.000	10.150	10.300
D1	0.295	0.307	0.319	7.500	7.800	8.100
D2	0.303	0.315	0.327	7.700	8.000	8.300
E	0.571	0.591	0.610	14.500	15.000	15.500
E1	0.337	0.341	0.348	8.550	8.700	8.850
E2	0.276	0.287	0.299	7.000	7.300	7.600
e	0.200BSC			5.080BSC		
L	0.070	---	0.110	1.790	---	2.790
L1	0.044	---	0.056	1.120	---	1.420
L2	0.030	---	0.070	0.770	---	1.770
L3	0.197REF			5.000REF		
θ	0°	---	8°	0°	---	8°

NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

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